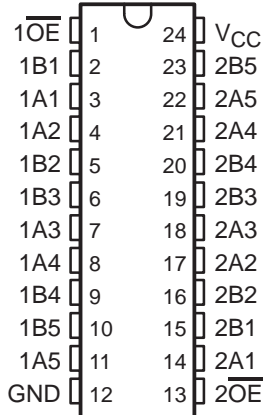


# SN54CBTD3384, SN74CBTD3384 10-BIT FET BUS SWITCHES WITH LEVEL SHIFTING

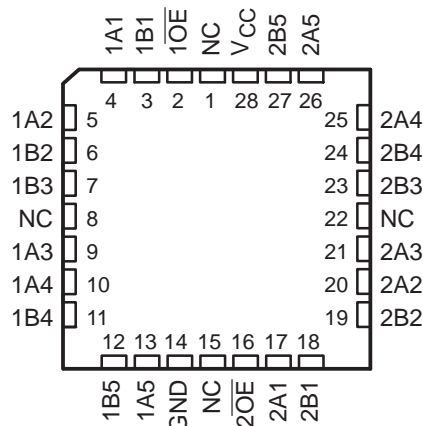
SCDS025R – MAY 1995 – REVISED JANUARY 2004

- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Designed to Be Used in Level-Shifting Applications

SN54CBTD3384 . . . JT OR W PACKAGE  
SN74CBTD3384 . . . DB, DBQ, DGV, DW, OR PW PACKAGE  
(TOP VIEW)



SN54CBTD3384 . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

## description/ordering information

The 'CBTD3384 devices provide ten bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switches allows connections to be made without adding propagation delay. A diode to V<sub>CC</sub> is integrated on the die to allow for level shifting from 5-V signals at the device inputs to 3.3-V signals at the device outputs.

These devices are organized as two 5-bit switches with separate output-enable ( $\overline{OE}$ ) inputs. When  $\overline{OE}$  is low, the switch is on, and port A is connected to port B. When  $\overline{OE}$  is high, the switch is open, and the high-impedance state exists between the two ports.

## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SOIC – DW	Tube	SN74CBTD3384DW	CBTD3384
		Tape and reel	SN74CBTD3384DWR	
	SSOP – DB	Tape and reel	SN74CBTD3384DBR	CC384
	SSOP (QSOP) – DBQ	Tape and reel	SN74CBTD3384DBQR	CBTD3384
	TSSOP – PW	Tube	SN74CBTD3384PW	CC384
		Tape and reel	SN74CBTD3384PWR	
	TVSOP – DGV	Tape and reel	SN74CBTD3384DGV	CC384
-55°C to 125°C	CDIP – JT	Tube	SNJ54CBTD3384JT	SNJ54CBTD3384JT
	CFP – W	Tube	SNJ54CBTD3384W	SNJ54CBTD3384W
	LCCC – FK	Tube	SNJ54CBTD3384FK	SNJ54CBTD3384FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

TEXAS  
INSTRUMENTS

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

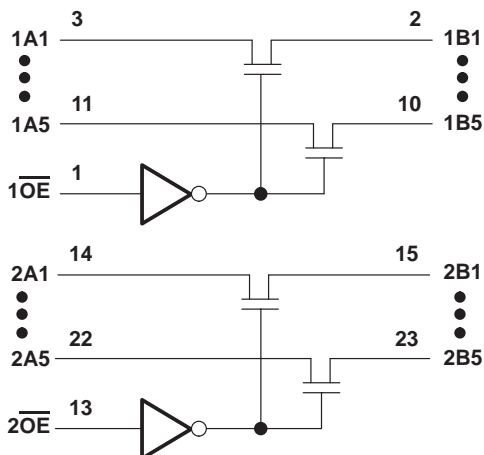
# SN54CBTD3384, SN74CBTD3384 10-BIT FET BUS SWITCHES WITH LEVEL SHIFTING

SCDS025R – MAY 1995 – REVISED JANUARY 2004

**FUNCTION TABLE**  
(each 5-bit bus switch)

INPUTS		INPUTS/OUTPUTS	
$\overline{1OE}$	$\overline{2OE}$	1B1–1B5	2B1–2B5
L	L	1A1–1A5	2A1–2A5
L	H	1A1–1A5	Z
H	L	Z	2A1–2A5
H	H	Z	Z

## logic diagram (positive logic)



Pin numbers shown are for the DB, DBQ, DGV, DW, JT, PW, and W packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	–0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, $I_{IK}$ ( $V_{I/O} < 0$ )	–50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	
DB package	63°C/W
DBQ package	61°C/W
DGV package	86°C/W
DW package	46°C/W
PW package	88°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.



# SN54CBTD3384, SN74CBTD3384 10-BIT FET BUS SWITCHES WITH LEVEL SHIFTING

SCDS025R – MAY 1995 – REVISED JANUARY 2004

## recommended operating conditions (see Note 3)

	SN54CBTD3384		SN74CBTD3384		UNIT
	MIN	MAX	MIN	MAX	
V <sub>CC</sub> Supply voltage	4.5	5.5	4.5	5.5	V
V <sub>IH</sub> High-level control input voltage	2		2		V
V <sub>IL</sub> Low-level control input voltage		0.8		0.8	V
T <sub>A</sub> Operating free-air temperature	-55	125	-40	85	°C

In applications with fast edge rates, multiple outputs switching, and operating at high frequencies, the output may have little or no level-shifting effect.

NOTE 3: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54CBTD3384		SN74CBTD3384		UNIT	
		MIN	TYP†	MAX	MIN		TYP†
V <sub>IK</sub>	V <sub>CC</sub> = 4.5 V, I <sub>I</sub> = -18 mA			-1.2		-1.2	V
V <sub>OH</sub>	See Figure 2						
I <sub>I</sub>	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 5.5 V or GND			±1		±1	μA
I <sub>CC</sub>	V <sub>CC</sub> = 5.5 V, I <sub>O</sub> = 0, V <sub>I</sub> = V <sub>CC</sub> or GND			1.5		1.5	mA
ΔI <sub>CC</sub> ‡	Control inputs V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND			2.5		2.5	mA
C <sub>i</sub>	Control inputs V <sub>I</sub> = 3 V or 0			3		3	pF
C <sub>io</sub> (OFF)	V <sub>O</sub> = 3 V or 0, $\overline{OE}$ = V <sub>CC</sub>			3.5		3.5	pF
r <sub>on</sub> §	V <sub>CC</sub> = 4.5 V	V <sub>I</sub> = 0	I <sub>I</sub> = 64 mA	5	5	7	Ω
			I <sub>I</sub> = 30 mA	5	5	7	
		V <sub>I</sub> = 2.4 V, I <sub>I</sub> = 15 mA	35	35	50		

† Typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

‡ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V<sub>CC</sub> or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

## switching characteristics over recommended ranges of supply voltage and operating free-air temperature range, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54CBTD3384		SN74CBTD3384		UNIT
			MIN	MAX	MIN	MAX	
t <sub>pd</sub> ¶	A or B	B or A		0.25		0.25	ns
t <sub>en</sub>	$\overline{OE}$	A or B	2.2	9.7	2.3	7	ns
t <sub>dis</sub>	$\overline{OE}$	A or B	1.5	8.6	1.7	5.3	ns

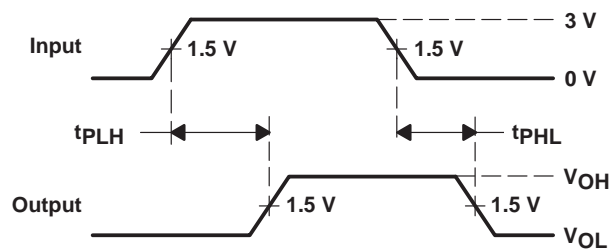
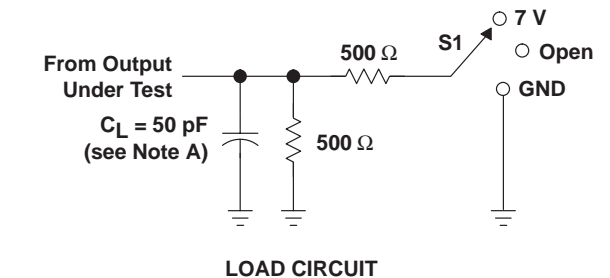
¶ The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



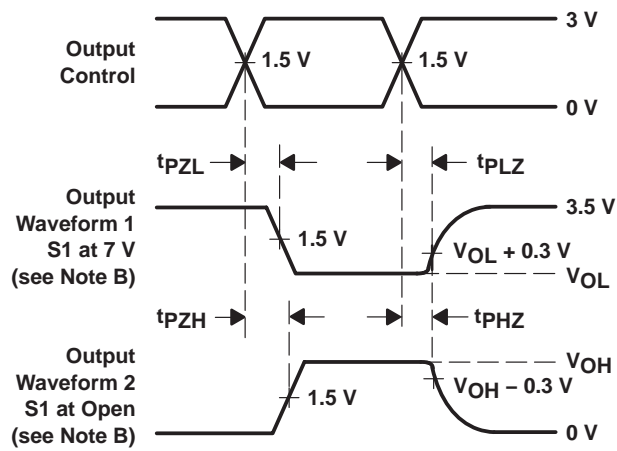
# SN54CBTD3384, SN74CBTD3384 10-BIT FET BUS SWITCHES WITH LEVEL SHIFTING

SCDS025R – MAY 1995 – REVISED JANUARY 2004

## PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>pd</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	7 V
t <sub>PHZ</sub> /t <sub>PZH</sub>	Open



- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
  - The outputs are measured one at a time with one transition per measurement.
  - t<sub>PZL</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
  - t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
  - t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

Figure 1. Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

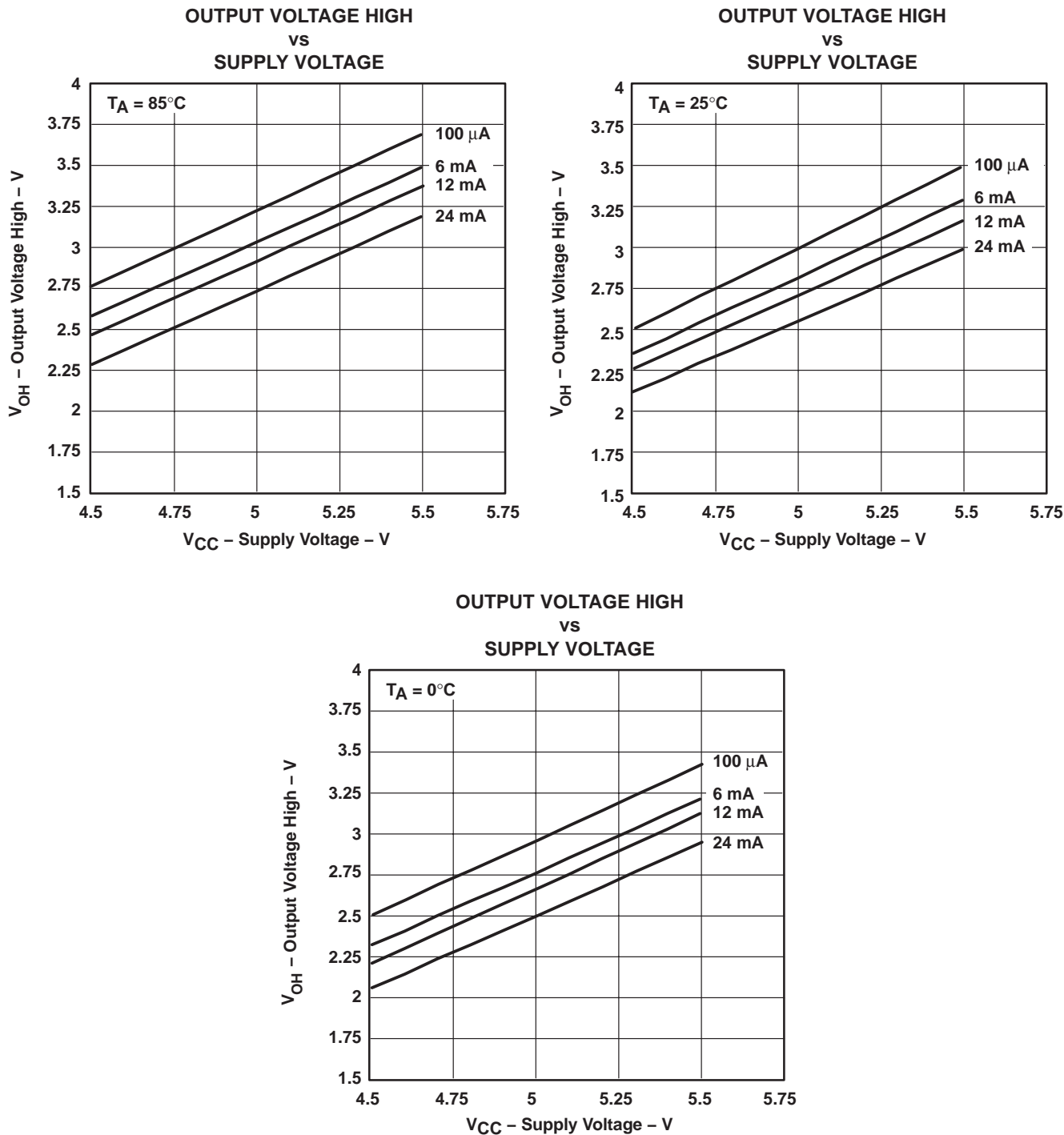


Figure 2.  $V_{OH}$  Values

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9752701Q3A	ACTIVE	LCCC	FK	28	42	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9752701Q3A SNJ54CBTD 3384FK	Samples
SN74CBTD3384DBQR	OBSOLETE	SSOP	DBQ	24		TBD	Call TI	Call TI	-40 to 85	CBTD3384	
SN74CBTD3384DBR	NRND	SSOP	DB	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CC384	
SN74CBTD3384DGVR	OBSOLETE	TVSOP	DGV	24		TBD	Call TI	Call TI	-40 to 85	CC384	
SN74CBTD3384DW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	-40 to 85	CBTD3384	
SN74CBTD3384DWR	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	-40 to 85	CBTD3384	
SN74CBTD3384PW	OBSOLETE	TSSOP	PW	24		TBD	Call TI	Call TI	-40 to 85	CC384	
SNJ54CBTD3384FK	ACTIVE	LCCC	FK	28	42	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9752701Q3A SNJ54CBTD 3384FK	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54CBTD3384, SN74CBTD3384 :**

● Catalog : [SN74CBTD3384](#)

● Military : [SN54CBTD3384](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBTD3384DBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1



**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBTD3384DBR	SSOP	DB	24	2000	356.0	356.0	35.0

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

DW (R-PDSO-G24)

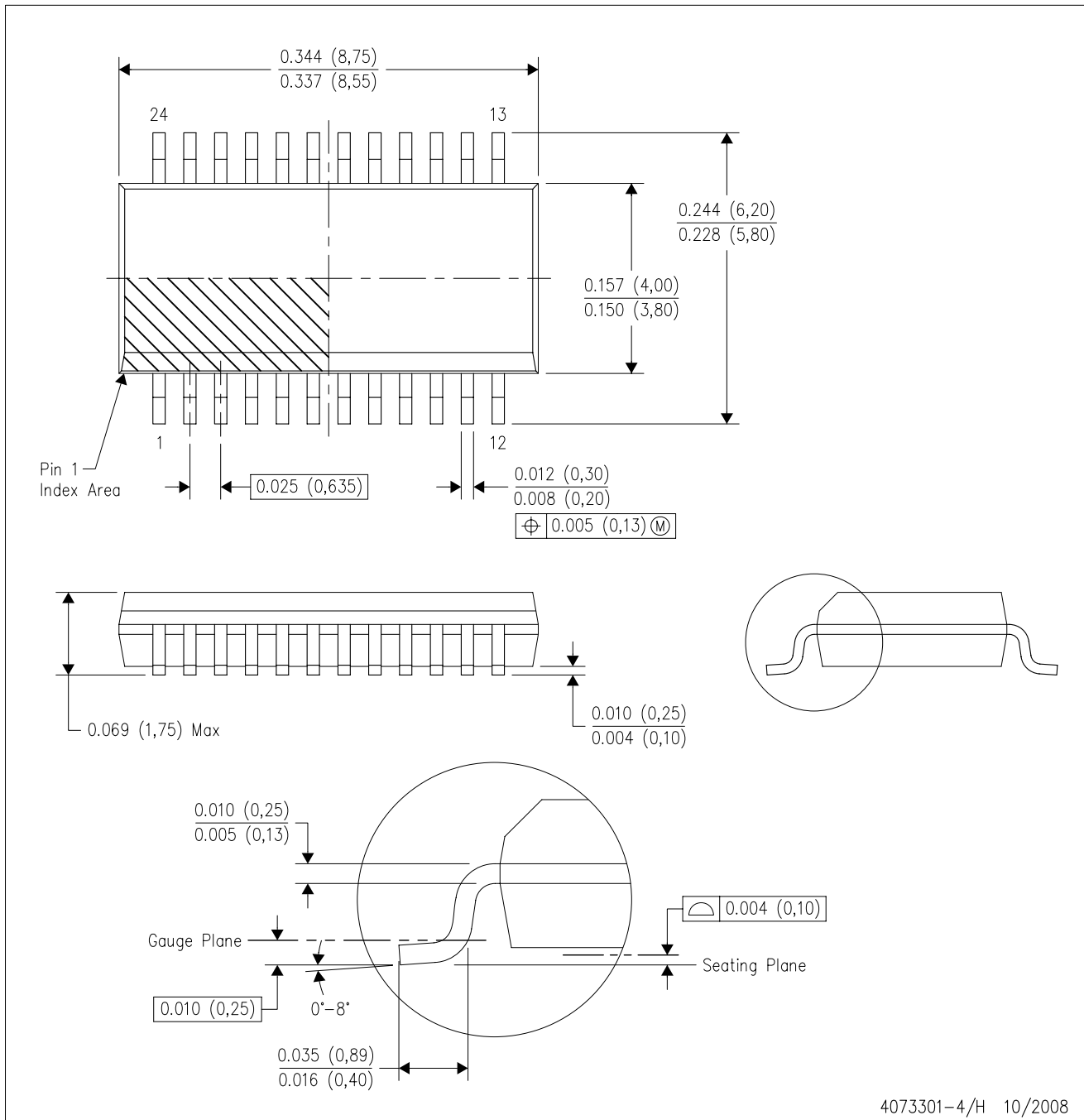
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AD.

DBQ (R-PDSO-G24)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
  - D. Falls within JEDEC MO-137 variation AE.

PW0024A



# PACKAGE OUTLINE

## TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220208/A 02/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4220208/A 02/2017

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DB (R-PDSO-G\*\*)

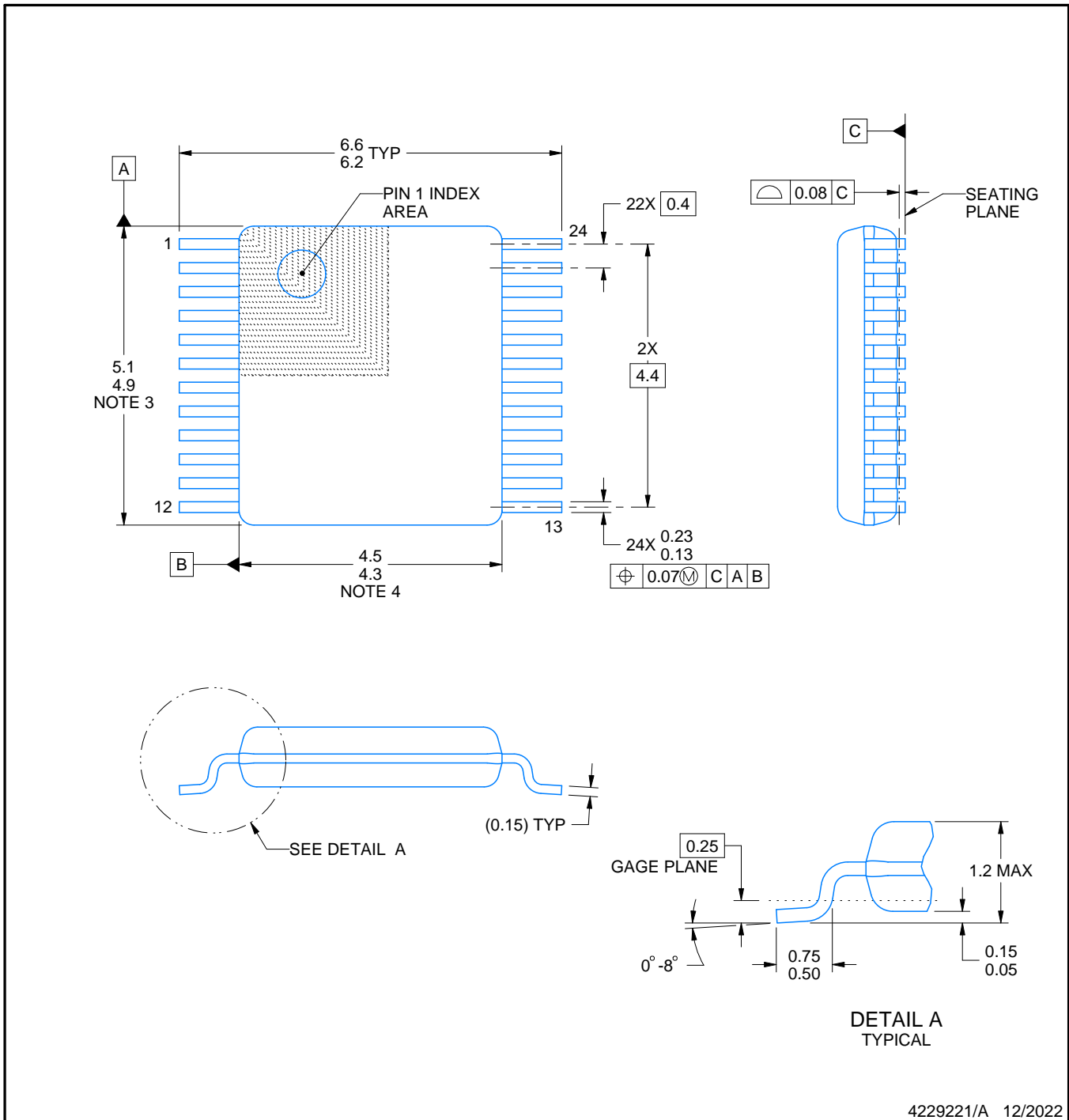
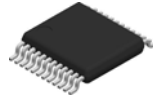
PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150





4229221/A 12/2022

NOTES:

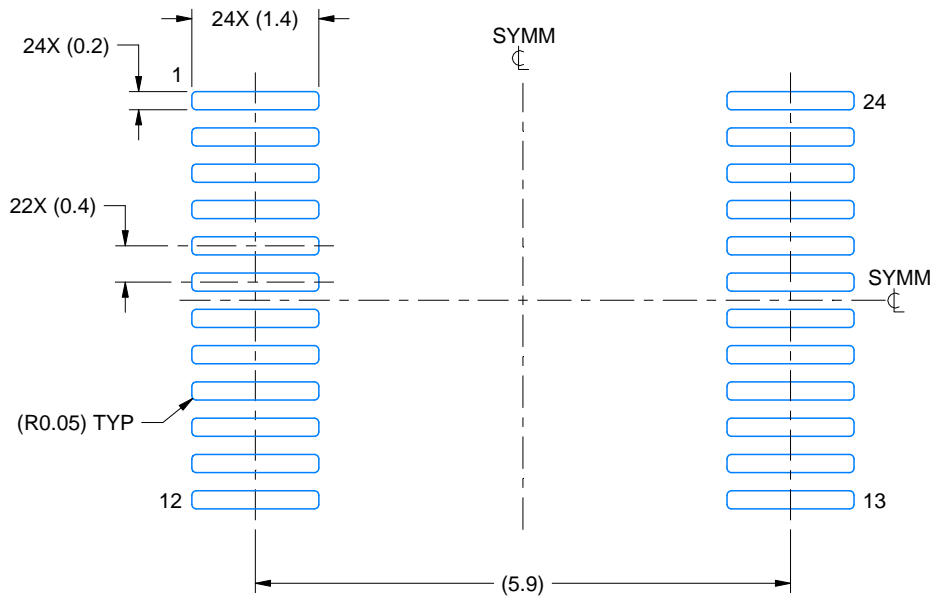
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

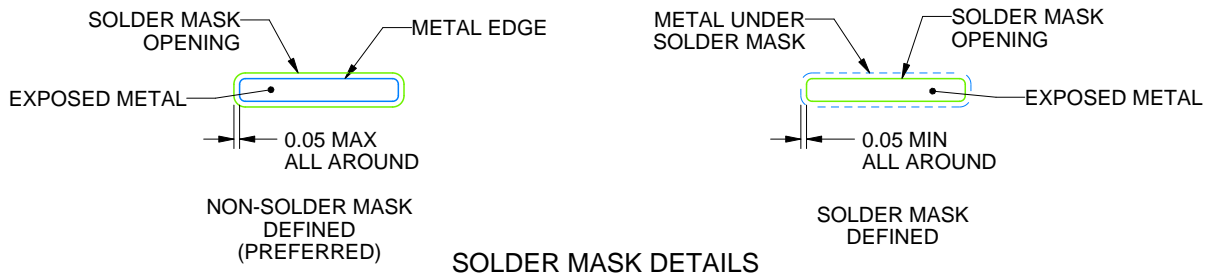
DGV0024A

TVSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 12X



SOLDER MASK DETAILS

4229221/A 12/2022

NOTES: (continued)

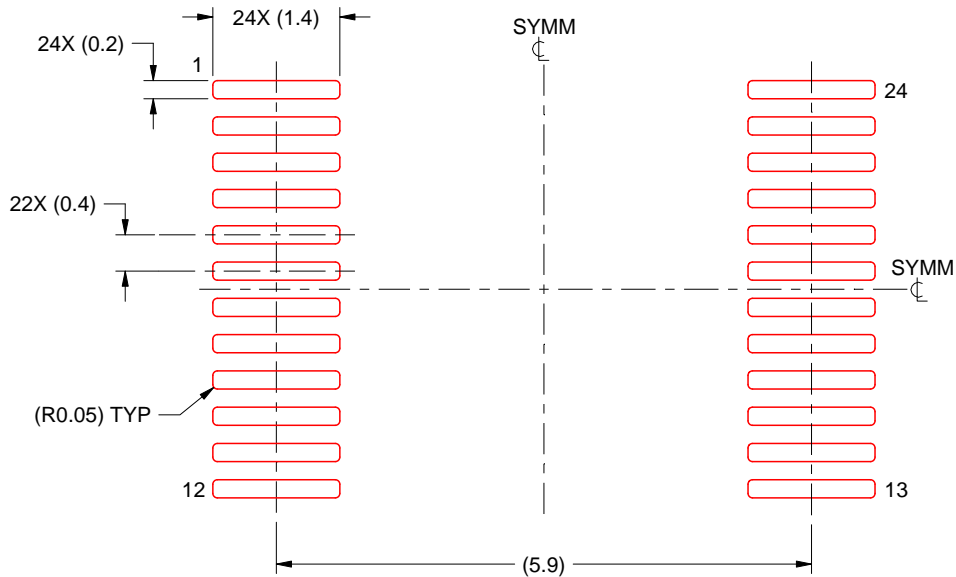
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DGV0024A

TVSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 12X

4229221/A 12/2022

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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